

IN THE CLAIMS:

1. (Previously Presented) An adhesive mold removing cleaning assembly comprising:

a liquid-permeable supporting sheet having a basis weight of 5 to 200 g/m²;

an active ingredient member comprising a mold removing ingredient, said active ingredient member having a thickness of not more than 5 mm;

a liquid-permeable adhesive member having a thickness of not more than 5 mm comprising a hydrophilic adhesive and a polyol plasticizer; and

an isolating layer having a basis weight of 2 to 100 g/m² which separates said active ingredient member from said adhesive member but which permits migration of said mold removing ingredient to at least a portion of said adhesive upon use;

wherein said hydrophilic adhesive is at least 30% by weight of said liquid-permeable adhesive member, said hydrophilic adhesive has a water content of 0.1% to 60% by weight,

wherein said adhesive member substantially covers one side of said isolating layer, and

said cleaning assembly upon use being adhered to an object to be cleaned by applying the adhesive member to a mold-

containing surface of the object whereby at least a portion of said adhesive contacts said mold and thereafter applying water thereto whereby said mold-removing ingredient passes through said adhesive to contact said mold.

2. (Cancelled)

3. (Previously Presented) An adhesive cleaning assembly according to claim 1, wherein said mold removing ingredient is provided on said supporting sheet, said isolating layer is provided on said active ingredient member to cover said active ingredient member, and said adhesive is provided on said isolating layer to form said adhesive member.

4. (Previously Presented) An adhesive cleaning assembly according to claim 1, wherein said adhesive member has a perforated structure having through-holes.

5. (Previously Presented) An adhesive cleaning assembly according to claim 1, wherein said adhesive member is a plurality of adhesive bands arranged in parallel in a width direction of said isolating layer.

6. (Cancelled)

7. (Previously Presented) The adhesive cleaning assembly according to claim 1, wherein said hydrophilic adhesive is selected from the group consisting of (i) a polymer having a salt-forming group, (ii) a nonionic water-soluble polymer, (iii) gelatin, (iv) an emulsion polymer, and (v) a crosslinked product of the polymers (i) to (iv).

8. (Previously Presented) The adhesive cleaning assembly according to claim 1, wherein said hydrophilic adhesive is a sodium styrenesulfonate/methacrylic acid copolymer.

9. (Previously Presented) The adhesive cleaning assembly according to claim 1, wherein said adhesive member further comprises an ingredient selected from the group consisting of a surfactant, a chelating agent and water.

10. (Previously Presented) The adhesive cleaning assembly according to claim 1, wherein said water content of said hydrophilic adhesive is 1% to 30% by weight.

11. (Currently Amended) An adhesive mold removing cleaning assembly comprising:

a) a liquid-permeable supporting sheet having a basis weight of 5 to 200 g/m²;

b) an active ingredient-containing sheet comprising a mold removing ingredient;

c) an adhesive layer having a thickness of not more than 5 mm comprising a hydrophilic adhesive and a polyol plasticizer; and

d) an isolating layer which separates said active ingredient member from said adhesive ~~member~~ layer but which permits migration of said mold removing ingredient to at least a portion of said adhesive ~~member~~ layer upon use;

wherein said hydrophilic adhesive comprises at least 30% by weight of said ~~liquid-permeable~~ adhesive ~~member~~ layer c),

wherein said active ingredient-containing sheet b) is laminated to said isolating layer d), whereby the surface of said active ingredient-containing sheet b) is covered with said isolating layer d), with said adhesive ~~member~~ layer covering at least a portion of said isolating layer opposite of said active ingredient-containing sheet, and

at least a portion of said adhesive ~~member~~ of said adhesive mold removing cleaning assembly upon use being adhered to the surface of an object to be cleaned by contacting at least a

portion of said liquid-permeable adhesive layer c) thereof with a mold-containing surface of the object and thereafter applying water thereto whereby said mold-removing ingredient passes through said adhesive to contact said mold.

12. (Previously Presented) The adhesive mold removing cleaning assembly of claim 1, wherein said isolating layer comprises spun lace nonwoven.

13. (Previously Presented) The adhesive mold removing cleaning assembly of claim 11, wherein said isolating layer comprises spun lace nonwoven.

14. (Previously Presented) The adhesive mold removing cleaning assembly of claim 18, wherein said isolating layer comprises a polyhydric alcohol.

15. (Cancelled)

16. (Currently Amended) The adhesive mold removing cleaning assembly of claim 14, wherein said polyhydric ~~alcohol~~ alcohol is polyethylene glycol.

17. (Cancelled)

18. (Currently Amended) An adhesive mold removing cleaning assembly comprising:

a liquid-permeable supporting sheet having a basis weight of 5 to 200 g/m²;

an adhesive layer having a thickness of not more than 5 mm comprising a hydrophilic adhesive and a polyol plasticizer;

said hydrophilic adhesive having admixed therewith a multitude of particles of a mold removing ingredient;

wherein said hydrophilic adhesive is at least 30% by weight of said adhesive layer and has a water content of 0.1% to 60% by weight;

the surface of each of said mold removing particles being coated with a water-soluble isolating layer to prevent contact between said mold removing particles and said hydrophilic adhesive; and

said cleaning assembly upon use being adhered to the surface of an object to be cleaned by applying the adhesive layer thereof to a mold-containing surface of the object whereby at least a portion of said adhesive contacts said mold and applying water thereto whereby said mold removing ingredient passes through said adhesive to contact said mold, and

wherein said adhesive layer has a perforated structure having through-holes.

19. (Previously Presented) The adhesive cleaning assembly according to claim 18, wherein said hydrophilic adhesive is selected from the group consisting of (i) a polymer having a salt-forming group, (ii) a nonionic water-soluble polymer, (iii) gelatin, (iv) an emulsion polymer, and (v) a crosslinked product of the polymers (i) to (iv).

20. (Previously Presented) The adhesive cleaning assembly according to claim 18, wherein said hydrophilic adhesive is a sodium styrenesulfonate/methacrylic acid copolymer.

21. (Currently Amended) The adhesive cleaning assembly according to claim 18, wherein said adhesive ~~member~~ layer further comprises an ingredient selected from the group consisting of a surfactant, a chelating agent and water.

22. (Previously Presented) The adhesive cleaning assembly according to claim 18, wherein said water content of said hydrophilic adhesive is 1% to 30% by weight.

23. (Previously Presented) The adhesive cleaning assembly according to claim 1, wherein said assembly has a thickness of from 0.2 to 10 mm.

24. (Previously Presented) The adhesive cleaning assembly according to claim 11, wherein said assembly has a thickness of from 0.2 to 10 mm.

25. (Previously Presented) The adhesive cleaning assembly according to claim 18, wherein said assembly has a thickness of from 0.2 to 10 mm.

26. (Currently Amended) The adhesive mold removing cleaning assembly of claim 11, wherein said adhesive ~~member~~ layer has a perforated structure having through-holes.

27. (Currently Amended) The adhesive mold removing cleaning assembly of claim 11, wherein said adhesive ~~member~~ layer comprises a plurality of spaced-apart adhesive bands.

28. (Cancelled)

29. (Currently Amended) The adhesive mold removing cleaning assembly of claim 18, wherein said adhesive ~~member~~ layer comprises a plurality of spaced-apart adhesive bands.

30. (New) An adhesive mold removing cleaning assembly comprising:

a liquid-permeable supporting sheet having a basis weight of 5 to 200 g/m²;

an adhesive layer having a thickness of not more than 5 mm comprising a hydrophilic adhesive and a polyol plasticizer;

said hydrophilic adhesive having admixed therewith a multitude of particles of a mold removing ingredient;

wherein said hydrophilic adhesive is at least 30% by weight of said adhesive layer and has a water content of 0.1% to 60% by weight;

the surface of each of said mold removing particles being coated with a water-soluble isolating layer to prevent contact between said mold removing particles and said hydrophilic adhesive;

said cleaning assembly upon use being adhered to the surface of an object to be cleaned by applying the adhesive layer thereof to a mold-containing surface of the object whereby at least a portion of said adhesive contacts said mold and applying water thereto whereby said mold removing ingredient passes through said adhesive to contact said mold, and

wherein said adhesive layer comprises a plurality of spaced-apart adhesive bands.

31. (New) The adhesive cleaning assembly according to claim 30, wherein said hydrophilic adhesive is selected from the group consisting of (i) a polymer having a salt-forming group, (ii) a nonionic water-soluble polymer, (iii) gelatin, (iv) an emulsion polymer, and (v) a crosslinked product of the polymers (i) to (iv).

32. (New) The adhesive cleaning assembly according to claim 30, wherein said hydrophilic adhesive is a sodium styrenesulfonate/methacrylic acid copolymer.

33. (New) The adhesive cleaning assembly according to claim 30, wherein said adhesive layer further comprises an ingredient selected from the group consisting of a surfactant, a chelating agent and water.

34. (New) The adhesive cleaning assembly according to claim 30, wherein said water content of said hydrophilic adhesive is 1% to 30% by weight.

35. (New) The adhesive cleaning assembly according to claim 30, wherein said assembly has a thickness of from 0.2 to 10 mm.